



- Drafts**
- BRS: warp and 1 and 2
 - BRS: 5 and
 - BRS:
- Pending**
- Active**
- L1: 106566: (diamond (uni nickel) adj5 diamond) garnet (silicon adj) carbide) sic
 - L2: 11779: 1 with particle
 - L3: 2354: 1 with (hard and particle)
 - L4: (6) 3 and (flip with chip)
 - L5: (669) 3 and (semiconductor chip die is (integrated adj) circuit)
 - L6: 1541: (ph board) pcb (printed adj) board) substrate) and 6
 - L7: 164: plated adj5 (plated adj4 (uni nickel))
 - L8: (6) 6 and 7
 - L9: 11716: (plated adj1 (uni nickel))
 - L10: 110: 5 and 6
- Failed**
- (6) (assy electromagnetic radiation if (loaded adj5 (silicone rubber urethanes carbon plastic film))
 - (6) 4 same 5
 - (6) 15 with 1
 - (6) (dummy with (semiconductor chip die is (integrated adj) circuit) and 10
- Saved**
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 - UNC
 - Queue
 - Trash

DB: ☐ USPAT ☐ US PGRUB ☐ EPO ☐ EPUB ☐ Synonym

Default operator: ☐ OR ☐ Highlight all hit terms only

and 9

☐ BRS Item
 ☐ E&R Item
 ☐ Image
 ☐ Text

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval C	Inventor	S	C	P	3
1	<input type="checkbox"/>	<input type="checkbox"/>	US 5331033:345 A1		15	Exhausted radiation member, power semiconductor				Areki, Kiyoshi , Kida, Masahiro	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
2	<input type="checkbox"/>	<input type="checkbox"/>	US 6109074 B1	20010206	27	Substrate material for mounting a semiconductor	429/472	429/323 : 428/305		Yamagata, Shinichi , et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
3	<input type="checkbox"/>	<input type="checkbox"/>	US 6117433 A	20000910	18	Micro texture media made by polishing of a selectively	427/537	427/128 : 427/150		Xong, Xavier , et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
4	<input type="checkbox"/>	<input type="checkbox"/>	US 6054193 A	20000425	19	Method for making CVD diamond coated substrate for	427/249.0	427/122 : 427/249.11		Zimmer, Jerry W. , et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
5	<input type="checkbox"/>	<input type="checkbox"/>	US 5930722 A	19991109	19	Plated aluminum alloy, cylinder block thereof,	205/219	205/640		Kuroda, Tetsuya , et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
6	<input type="checkbox"/>	<input type="checkbox"/>	US 5921856 A	19990713	14	CVD diamond coated substrate for polishing pad	451/539	451/526		Zimmer, Jerry W.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
7	<input type="checkbox"/>	<input type="checkbox"/>	US 5759607 A	19980602	9	Diamond wire drawing die and process for manufacturing	429/132	429/131 : 428/212		Takahashi, Toshiya , et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
8	<input type="checkbox"/>	<input type="checkbox"/>	US 5521236 A	19961105	9	Diamond wire drawing die	72/467			Takahashi, Toshiya , et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
9	<input type="checkbox"/>	<input type="checkbox"/>	US 5275792 A	19931228	44	Coated parts with film having powder skeleton	427/242	205/83 : 427/11		Sagawa, Masato , et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
10	<input type="checkbox"/>	<input type="checkbox"/>	US 5269839 A	19931214	9	Electroless plating solution and plating method with it	106/1,22	106/1,27 : 427/438		Inoue, Manabu , et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

File Edit

Ready

Drafts

- ☐ BRS: warp 1 and 2
- ☐ BRS: 4 and
- ☐ BRS:
- ☐ BRS: 11 and

Pending

Active

- ☐ L1: (194466) (diamond (ni nickel) adj5 diamond; garnet (silicon adj carbide) sio)
- ☐ L2: (17778) 1 with particle
- ☐ L3: (1454) 1 with (hard and particle)
- ☐ L4: (8) 2 and (chip with chip)
- ☐ L5: (860) 3 and (semiconductor chip diw in (integrated adj circuit))
- ☐ L6: (540) (pb board pcb cb (printed adj3 board; substrate) and 1
- ☐ L7: (564) (plated adj5 (plated adj4 (ni nickel))
- ☐ L8: (1) 6 and 7
- ☐ L9: (11712) (plated adj5 (ni nickel))
- ☐ L10: (11) 3 and 4
- ☐ L11: (83) (pb board pcb cb (printed adj3 board)) and 5
- ☐ L12: (1) 11 and 4
- ☐ L13: (10) 438.97.ccls.
- ☐ L14: (114610) 438/97.ccls.
- ☐ L15: (127507) 257/97.ccls.
- ☐ L16: (228613) 14 15
- ☐ L17: (22) 15 and 21

Failed

- ☐ (1) (loopy electromagnetic radiation rt (loaded adj5 (silicone rubber urethanes carbon plastic fra...
- ☐ (1) 4 base 5
- ☐ (1) 15 with 1
- ☐ (1) (diode with (semiconductor chip diw in (integrated adj circuit)) and 17

DB: ☐ USPAT, ☐ US PGPUB, ☐ EPO, ☐ Eureka, ☐ Synonym

Default operator: ☐ OR ☐ Highlight all 14 terms only

16 and 11

☐ BRS Item ☐ Edit Item ☐ Image ☐ Text

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval C	Inventor	S	C	P	3
1	<input type="checkbox"/>	<input type="checkbox"/>	US 6166432 A	20001026	11	Substrate for use in wafer attracting apparatus and	257/701	277/128		Ohno, Masashi , et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
2	<input type="checkbox"/>	<input type="checkbox"/>	US 5934335 A	19981110	5	Non-metallurgical connection between an integrated	438/107	438/130		Euschnow, Milton L.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
3	<input type="checkbox"/>	<input type="checkbox"/>	US 4979015 A	19901018	26	Printed circuit board with inorganic insulating matrix	257/747	174/258		Pequette, Edward L. , et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

Ready